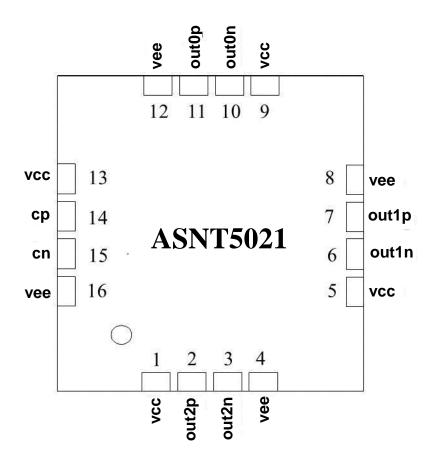


Ultra High-Speed Mixed Signal ASICs

Offices: 310-530-9400 / Fax: 310-530-9402 www.adsantec.com

ASNT5021-PQD DC-26*Gbps*/13*GHz* Signal Distributor 1-to-3

- High-speed broadband Data/Clock Amplifier and Distributor
- Exhibits low jitter and limited temperature variation over industrial temperature range
- One input differential signal port and three differential amplified output signal ports
- Matched phase delays for all outputs
- Fully differential CML input interface
- Fully differential CML output interfaces with 600mV single-ended swing
- Single +3.3V or -3.3V power supply
- Power consumption: 780*mW*
- Fabricated in SiGe for high performance, yield, and reliability
- Standard MLF/QFN 16-pin package





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DESCRIPTION

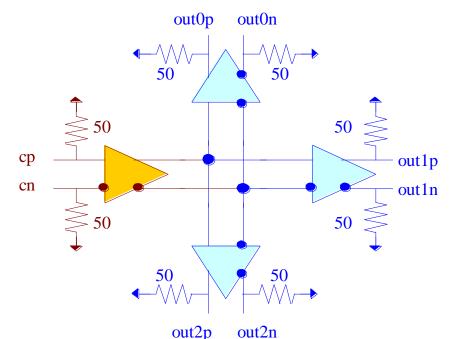


Fig. 1. Functional Block Diagram

The temperature stable ASNT5021-PQD SiGe IC provides active broadband data/clock signal splitting, and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can deliver three phase-matched copies of the broadband data/clock input signal cp/cn to three high-speed differential outputs out0p/out0n, out1p/out1n, out2p/out2n.

The part's I/O's support the CML logic interface with on chip 50*Ohm* termination to vcc and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

POWER SUPPLY CONFIGURATION

The part can operate with either negative supply (vcc = 0.0V = ground and vee = -3.3V), or positive supply (vcc = +3.3V and vee = 0.0V = ground). In case of the positive supply, all I/Os need AC termination when connected to any devices with 50*Ohm* termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume vcc = 0.0V and vee = -3.3V.



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ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	V
Power Consumption		0.86	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	°С
Storage Temperature	-40	+100	°С
Operational Humidity	10	98	%
Storage Humidity	10	98	%

Table 1. Absolute	Maximum	Ratings
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TERMINAL FUNCTIONS

TERMINAL		4L	DESCRIPTION		
Name	No.	Туре			
	High-Speed I/Os				
ср	14	CML	Differential high speed data/clock inputs with internal SE 500hm		
cn	15	input	termination to VCC		
out0p	11	CML	Differential high speed data/clock outputs with internal SE 500hm		
out0n	10	output	termination to vcc. Require external SE 500hm termination to vcc		
out1p	7	CML	Differential high speed data/clock outputs with internal SE 500hm		
out1n	6	output	termination to vcc. Require external SE 500hm termination to vcc		
out2p	2	CML	Differential high speed data/clock outputs with internal SE 500hm		
out2n	3	output	termination to vcc. Require external SE 50 <i>Ohm</i> termination to vcc		
Supply and Termination Voltages					
Name Description			scription	Pin Number	
vcc	Positive power supply $(+3.3V \text{ or } 0)$			1, 5, 9, 13	
vee	Negative power supply $(0V \text{ or } -3.3V)$			4, 8, 12, 16	



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ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
	General Parameters				
vee	-3.1	-3.3	-3.5	V	±6%
VCC		0.0		V	External ground
Ivee		235		mА	
Power consumption		780		mW	
Junction temperature	-40	25	125	°C	
HS Input Data/Clock (cp/cn)					
Data Rate	DC		26	Gbps	
Frequency	DC		13	GHz	
Swing	0.05		1.0	V	Differential or SE, p-p
CM Voltage Level	vcc-0.8		VCC	V	Must match for both inputs
HS Output Data/Clock (out0p/out0n, out1p/out1n, out2p/out2n)					
Data Rate	DC		26	Gbps	
Frequency	DC		13	GHz	
Phase mismatch			2	ps	Between any two SE outputs
Logic "1" level		VCC		V	
Logic "0" level		vcc- 0.6		V	With external 500hm DC termination
Rise/Fall times	13		17	ps	20%-80%
Additive Jitter			5	ps	Peak-to-peak
Duty cycle	45	50	55	%	For clock signal

PACKAGE INFORMATION

The chip die is housed in a standard 16-pin QFN package shown in Fig. 2. It is recommended that the center heat slug located on the back side of the package is soldered to the **vee** plain that is ground for the positive supply or power for the negative supply.

The part's identification label is ASNT5021-PQD. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per 2011/65/EU for all ten substances.





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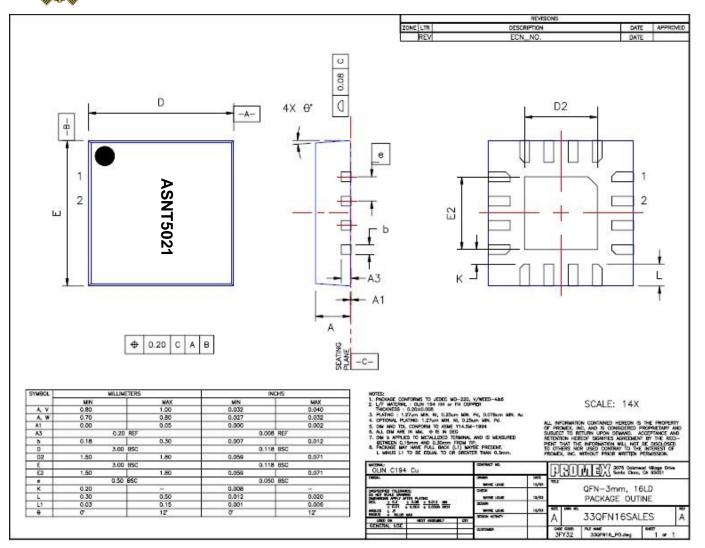


Fig. 2. QFN 16-Pin Package Drawing (All Dimensions in mm)





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REVISION HISTORY

Revision	Date	Changes		
3.2.2	05-2020	Updated Package Information		
3.1.2	07-2019	Updated Letterhead		
3.1.1	03-2013	Added phase mismatch specifications		
		Revised electrical characteristics table		
		Updated description		
3.0.1	02-2013	Revised title		
		Revised description		
		Added power supply configuration		
		Added absolute maximum ratings		
		Revised terminal functions		
		Revised electrical characteristics		
		Revised package information		
		Added mechanical drawing		
		Format correction		
2.0	12-2008	Revised electrical characteristics section		
		Revised package information section		
1.0	10-2008	Initial release		